VRFA0156-BD



9-10GHz 41.5dBm GaAs MMIC Power Amplifier

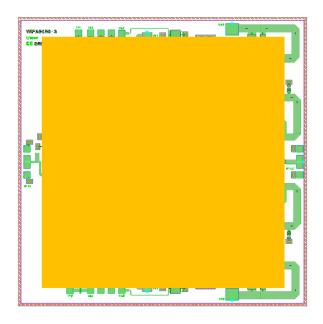
Advanced Product information v1

Features

- Frequency Range: 9 to 10 GHz
- Single supply +7.5V
- 30dB small signal gain
- 50% Drain Efficiency @ 9.5GHz typical
- Rugged power handling capability
- 50Ω matched RF ports
- Die size = 4.40mm x 4.45mm

Description

The VRFA0156-BD is a GaAs high power amplifier MMIC which operates over the frequency range of 8.5GHz to 10.5GHz. The amplifier typically delivers a small signal gain of +30dB, saturated output power Psat of +41.6dBm with a typical efficiency of 50% at 9.5GHz. The RF ports are DC blocked and matched to 50Ω .



Electrical Specifications

T=+25°C baseplate, V_{DD} = +7.5V

D	Specification				
Parameter	Min.	Typ @9.5GHz	Max.	Unit	
Frequency Bandwidth	9		10	GHz	
Small Signal Gain		30		dB	
I/P Return Loss		-17.4		dB	
O/P Return Loss		-15.2		dB	
Saturated Output Power (Psat)		41.6		dBm	
Power Added Efficiency (PAE)		50		%	

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Simulated Performance

T=+25°C baseplate, V_{DD} = +7.5V

43.0-

42.5-

42.0-

41.5

41.0

40.5-

40.0

8.4

8.6

8.8 9.0

Pout (dBm)

No bondwire

With bondwire

Simulated VRFA0156V1 S-Parameter



No bondwire

ا 9.2 9.4

9.6

RFfreq

9.8

Simulated VRFA0156V1 Pout and PAE

With bondwire

freq, GHz

10.0 10.5 11.0 11.5 12.0

7.0 7.5 8.0 8.5 9.0 9.5

-60

-55

-50

45

-40

-35

-30

-25

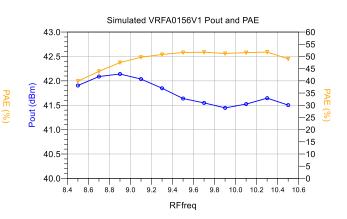
-20 -15

-10

-5

-0

10.0 10.2 10.4 10.6





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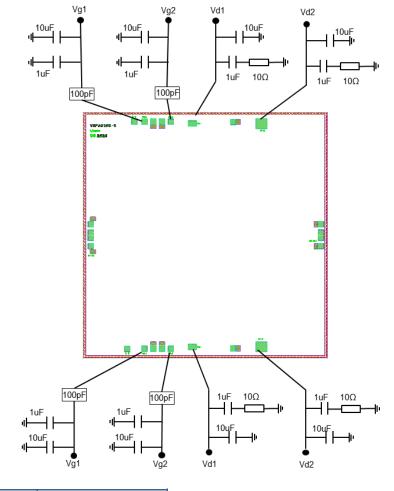
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Recommended Absolute Maximum Ratings [1]

Parameter	Symbol	Value	Notes
Drain Bias Voltage	V _d	+8.5V	
Gate Bias Voltage	Vg	-5V	
Gate Current	l _g	20mA	
Junction Temperature	Tj	175°C	For maximum median device lifetime, T _i should be minimised
Storage temperature	$T_{storage}$	-55 to 150°C	

^[1] Operation outside these conditions may cause permanent damage to the device. Combination of maximum rating conditions may reduce the values. Device performance at these ratings is not implied.

Assembly & Bond-



Die thickness	100um	GaAs devices are ESD sensitive and
Minimum bond pad opening	100 um v 100 um	precautions should be observed during
		storage, handling, assembly and testing.

